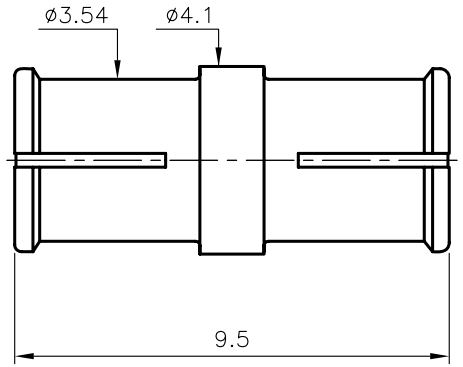
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	I.C.KIM	2014.11.17.
1	[설변No.201506-0020] PIN 내경 치수 변경	H.J.LEE	I.C.KIM	2015.06.19.
2	부적합 개선 치수 수정	S.M.LEE	I.C.KIM	2015.10.02.



NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
3	INSULATOR	1	TEFLON		DAI00149-N/3
2	CONTACT	1	BeCu	Silver Plate	DAC00276-5/4
1	BODY	1	BeCu	SUCO Plate	DAD00280-5/4

TOLERANCE	Decimal ±0.1	DATE	2015. 10. 02.
	Angle ±1°	APPROVED BY	I.C.KIM
		CHECKED BY	H.J.LEE
MATERIAL	-	DRAWN BY	S.M.LEE
FINISH	-	SCALE 6/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.
RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
Fax : 82-32-347-8017

TITLE
SMP MAX (J) SMP MAX (J) ST

A4

DWG NO. AD00527-7/3
REVISION 2
SHEET 1 of 1